



VMDSEMI

**VUDD003R250PA**

**Datasheet**



VMDSEMI

## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
-30V	25mΩ@-10V	-9A
	35mΩ@-4.5V	

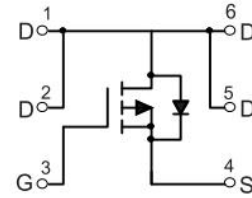


Figure 1 Symbol of VUDD003R250PA

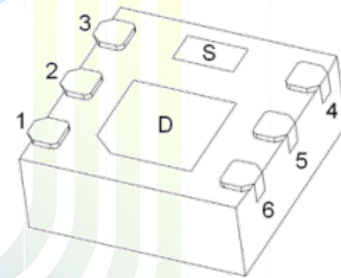
## Features

- Trench Technology Power MOSFET
- Low  $R_{DS(ON)}$
- Low Gate Charge

## Application

- Load Switch
- DC/DC Converter

## Package Type



**DFN2X2-6L**

Figure 2 Package Type of VUDD003R250PA

## Ordering Information

Product Name	Package
VUDD003R250PA	DFN2X2-6L

**Absolute Maximum Ratings** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	-30	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current <sup>Note1</sup>	$I_D$	-9	A
Pulsed Drain Current <sup>Note2</sup>	$I_{DM}$	-36	
Total Power Dissipation <sup>Note4</sup>	$P_D$	0.75	W
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 to 150	$^\circ\text{C}$

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note5</sup>	$R_{\theta JA}$		165		$^\circ\text{C}/\text{W}$



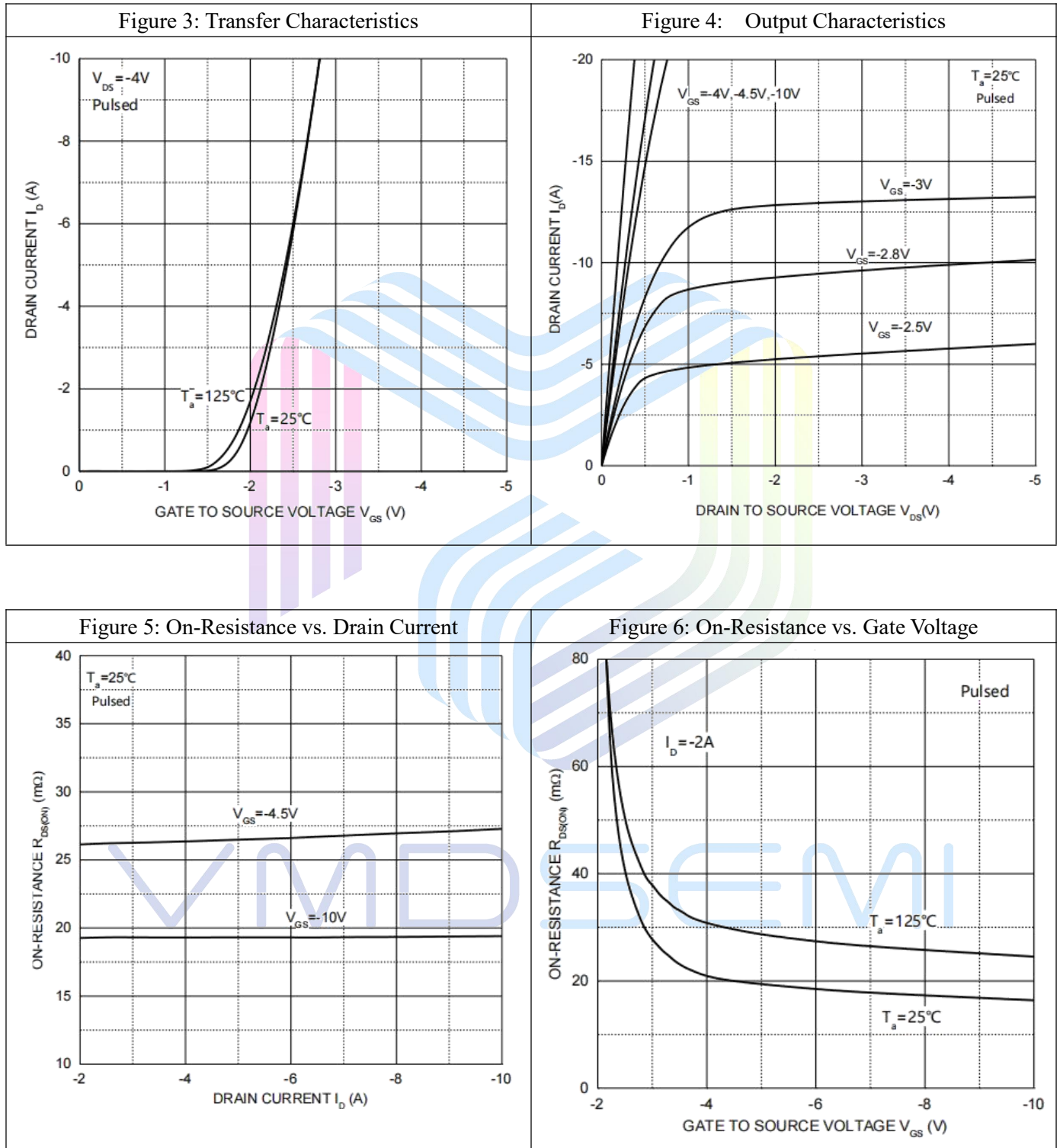
**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)

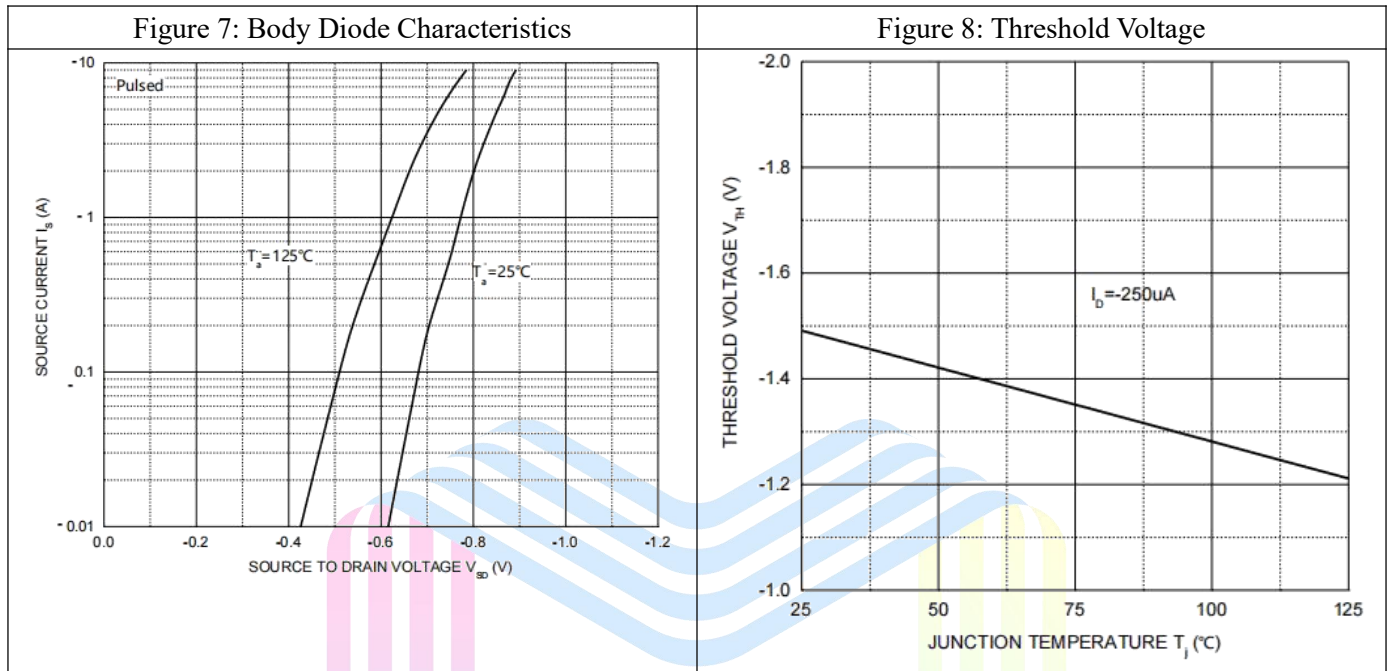
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	-30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-24V, V_{GS}=0V$			-1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage <sup>Note3</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0	-1.5	-3.0	V
Static Drain-Source On-Resistance <sup>Note3</sup>	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-9A$		19	25	mΩ
		$V_{GS}=-4.5V, I_D=-7A$		27	35	
Forward Transconductance <sup>Note3</sup>	$g_{FS}$	$V_{DS}=-10V, I_D=-9.1A$		12		S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=-15V$		1400		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		163		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		145		pF
Total Gate Charge	$Q_g$	$V_{DS}=-15V$			25	nC
Gate-Source Charge	$Q_{gs}$	$V_{GS}=-4.5V$			7	
Gate-Drain Charge	$Q_{gd}$	$I_D=-9.1A$			12	
<b>Switching Parameters</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-15V$			15	ns
Turn-on Rise Time	$t_r$	$V_{GS}=-10V$			15	
Turn-off Delay Time	$t_{d(off)}$	$R_L=15\Omega$			70	
Turn-off Fall Time	$t_f$	$R_G=1\Omega, I_D=-1A$			25	
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note3</sup>	$V_{SD}$	$V_{GS}=0V, I_S=-2A$			-1.2	V
Diode Forward Current	$I_S$				-9	A

Notes :

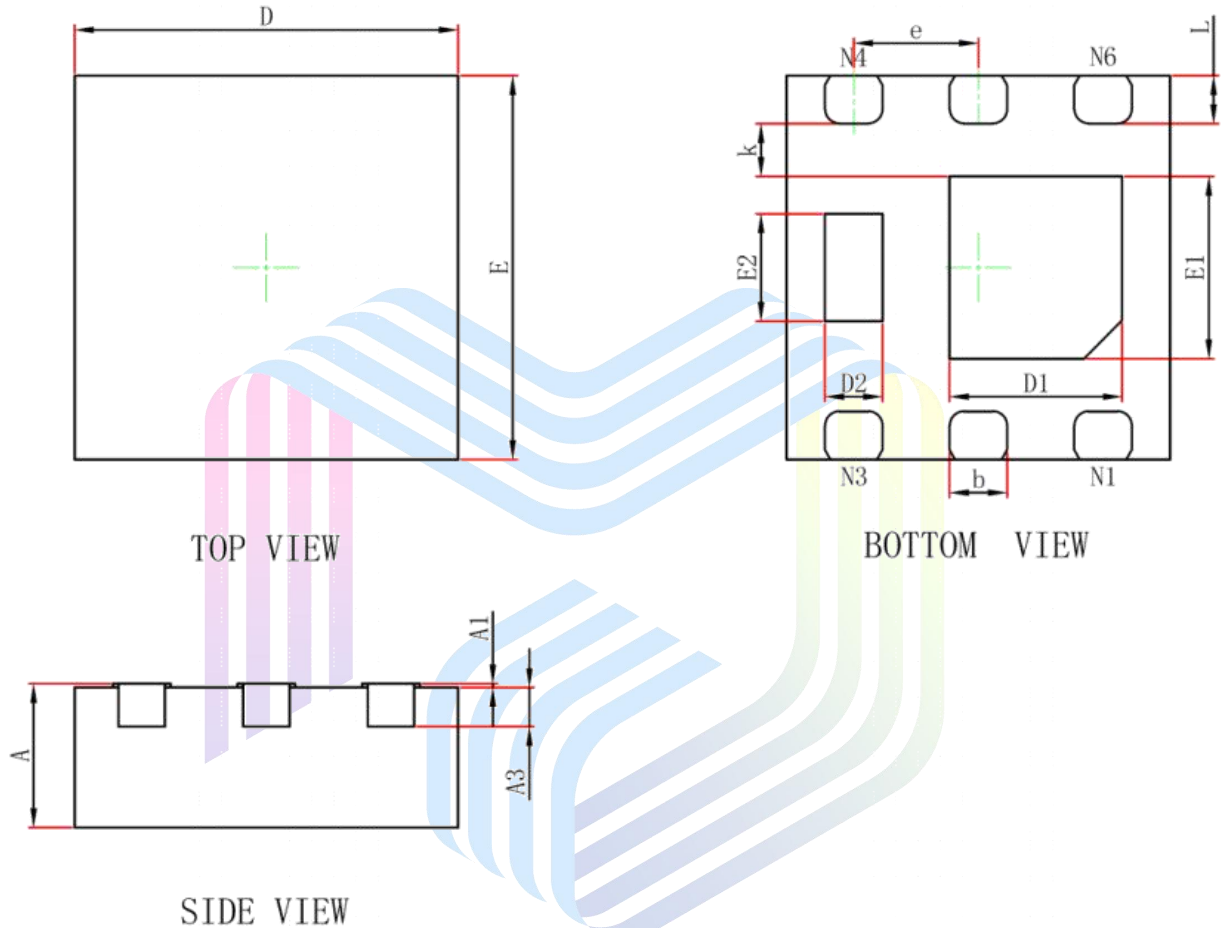
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 4.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ .And device mounted on a large heatsink
- 5.Device mounted on  $1in^2$  FR-4 board with 2oz Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

## Typical Performance Characteristics





# VMDSEMI

**Mechanical Dimensions:**
**DFN2X2-6L Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0	0.050	0	0.002
A3	2.03REF		0.008REF	
D	1.900	2.100	0.075	0.083
E	1.900	2.100	0.075	0.083
D1	0.800	1.000	0.031	0.039
E1	0.850	1.050	0.033	0.041
D2	0.200	0.400	0.008	0.016
E2	0.460	0.660	0.018	0.026
k	0.200MIN		0.008MIN	
b	0.250	0.350	0.010	0.014
e	0.65BSC		0.026TYP	
L	0.174	0.326	0.007	0.013

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